

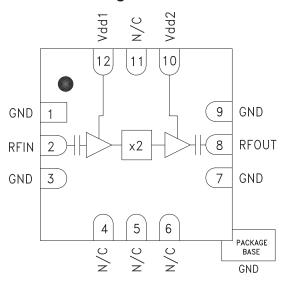


Typical Applications

The HMC578LC3B is suitable for:

- Clock Generation Applications:
 SONET OC-192 & SDH STM-64
- Point-to-Point & VSAT Radios
- Test Instrumentation
- Military & Space

Functional Diagram



Features

High Output Power: +15 dBm

Low Input Power Drive: 0 to +6 dBm
Fo Isolation: >20 dBc @ Fout= 28 GHz
100 KHz SSB Phase Noise: -132 dBc/Hz

Single Supply: +5V@ 81 mA

RoHS Compliant 3x3 mm SMT Package

General Description

The HMC578LC3B is a x2 active broadband frequency multiplier utilizing GaAs PHEMT technology in a leadless RoHS compliant SMT package. When driven by a +3 dBm signal, the multiplier provides +15 dBm typical output power from 24 to 33 GHz. The Fo and 3Fo isolations are >20 dBc and >30 dBc respectively at 28 GHz. The HMC578LC3B is ideal for use in LO multiplier chains for Pt to Pt & VSAT Radios yielding reduced parts count vs. traditional approaches. The low additive SSB Phase Noise of -129 dBc/Hz at 100 kHz offset helps maintain good system noise performance. The RoHS packaged HMC578LC3B eliminates the need for wire bonding, and allows the use of surface mount manufacturing techniques.

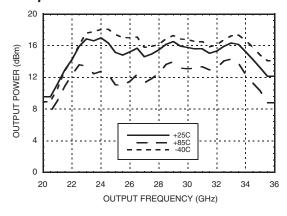
Electrical Specifications, $T_A = +25^{\circ}$ C, Vdd1, Vdd2 = +5V, 3 dBm Drive Level

Parameter	Min.	Тур.	Max.	Units
Frequency Range, Input	12 - 16.5		GHz	
Frequency Range, Output	24 - 33		GHz	
Output Power	10	15		dBm
Fo Isolation (with respect to output level)		20		dBc
3Fo Isolation (with respect to output level)		30		dBc
Input Return Loss		10		dB
Output Return Loss		12		dB
SSB Phase Noise (100 kHz Offset)		-132		dBc/Hz
Supply Current (Idd1 & Idd2)		81		mA

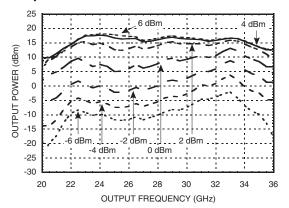




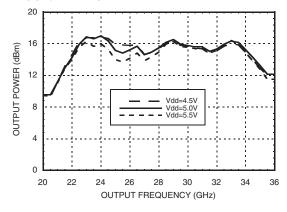
Output Power vs. Temperature @ 3 dBm Drive Level



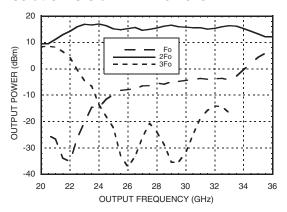
Output Power vs. Drive Level



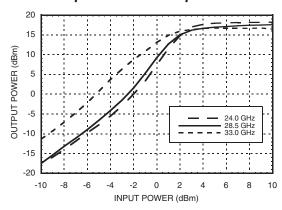
Output Power vs. Supply Voltage @ 3 dBm Drive Level



Isolation @ 3 dBm Drive Level



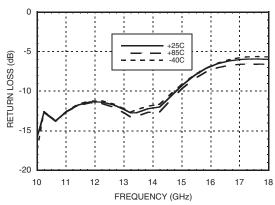
Output Power vs. Input Power



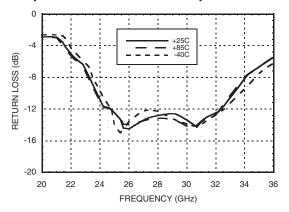




Input Return Loss vs. Temperature



Output Return Loss vs. Temperature







Absolute Maximum Ratings

RF Input (Vdd = +5V)	+13 dBm	
Supply Voltage (Vdd)	+6.0 Vdc	
Channel Temperature	175 °C	
Continuous Pdiss (T= 85 °C) (derate 7.4 mW/°C above 85 °C)	670 mW	
Thermal Resistance (channel to ground paddle)	135 °C/W	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-40 to +85 °C	

Typical Supply Current vs. Vdd

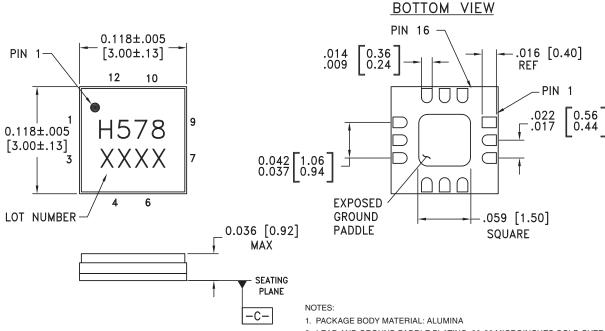
Vdd (Vdc)	Idd (mA)		
4.5	81		
5.0	81		
5.5	81		

Note

Multiplier will operate over full voltage range shown above.



Outline Drawing



- 2. LEAD AND GROUND PADDLE PLATING: 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM -C-
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. CLASSIFIED AS MOISTURE SENSITIVITY LEVEL (MSL) 1.





Pin Description

Pin Number	Function	Description	Interface Schematic	
1, 3, 7, 9	GND	Package bottom must also be connected to RF/DC ground.	GND =	
2	RFIN	Pin is AC coupled and matched to 50 Ohms from 12 - 16.5 GHz.	RFIN ○──	
4 - 6, 11	N/C	These pins are internally not connected; however, this product was specified with these pins connected to RF/ DC ground.		
8	RFOUT	Pin is AC coupled and matched to 50 Ohms from 24 - 33 GHz.	— —ORFOUT	
10, 12	Vdd2, Vdd1	Supply voltage 5V \pm 0.5V. External bypass capacitors of 100 pF, 1,000 pF and 2.2 μ F are required.	Vdd1, Vdd2	

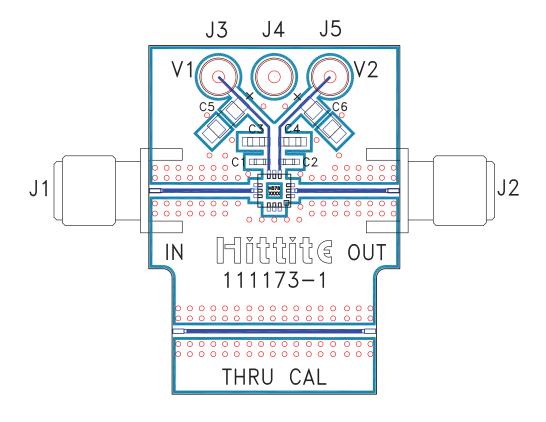
Application Circuit

Component	Value		J3 (\supset	○ J5	
C1, C2	100 pF			Ĭ		
C3, C4	1,000 pF	$C1 \stackrel{\checkmark}{=} C3 \stackrel{\checkmark}{=} C$	$-$ 5 \perp		C2	C4 \(\preccent{+} \) C6 \(\preccent{+} \)
C5, C6	2.2 μF		" <u>工</u>			
			12		10	
				ld1 Vo	dd2	
		O	2 RFIN	MC578LC	RFOUT	8 J2
				GND 1,3	5,7,9	





Evaluation PCB



List of Materials for Evaluation PCB 112409 [1]

Item	Description
J1, J2	PCB Mount SRI K Connector
J3 - J5	DC Pin
C1, C2	100 pF Capacitor, 0402 Pkg.
C3, C4	1,000 pF Capacitor, 0603 Pkg.
C5, C6	2.2 µF Tantalum Capacitor
U1	HMC578LC3B x2 Active Multiplier
PCB [2]	111173 Eval Board

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350